



Material Content Data Sheet



Sales Product Name		IPB180N04S4-00		Issued		25. January 2018		
MA#		MA000669394						
Package		PG-TO263-7-3		Weight*		1540.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.245	0.66	0.66	6648	6648
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		156	
	non noble metal	copper	7440-50-8	801.714	52.03	52.10	520270	520948
wire	non noble metal	aluminium	7429-90-5	133.175	8.64	8.64	86423	86423
encapsulation	organic material	carbon black	1333-86-4	7.037	0.46		4567	
	plastics	epoxy resin	-	77.412	5.02		50236	
	inorganic material	silicondioxide	60676-86-0	384.712	24.97	30.45	249658	304461
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	7993	7993
plating	non noble metal	nickel	7440-02-0	0.269	0.02		175	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	175
solder	noble metal	silver	7440-22-4	0.167	0.01		108	
	non noble metal	tin	7440-31-5	0.134	0.01		87	
	non noble metal	lead	7439-92-1	6.384	0.41	0.43	4143	4338
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.89	6.90	68924	69014
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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